

## **Bill of Materials**

## TI DESIGNS

Desimates	Malara	D. controller	B. C.	MEO Boot Noveles	0:	Ownertities
Designator	Value	Description			<b>Size</b> 0805	Quantity
C1, C2, C3, C5, C6, C10, C14, C15, C17, C19, C23	0.1uF	Capacitor	Kemet	C0805C104K5RACTU		11
C4	100uF	100uF, 50V Electrolytic Cap	Panasonic	ECA-1HM101	RB .2/.4 SS	1
C7, C8, C9	.22uF	Capacitor	Kemet		0805	3
C11, C12, C13	1000 pf	Capacitor			0805	3
C16, C18, C22	10uF	10uF, 25V Electrolytic Cap (Radial)		UVR1E100MDD	RB .1/.250	3
C20, C21	33pF	Capacitor			0805	2
D1, D10, D11	LED RED	LED RED Clear 1206 SMD	Stanley Electric & Co	HBR1105W-TR	1206	3
D2, D3, D4, D5, D6, D7, D8, D9	MBR360	3A, 60V, Schottky Diode	On Semiconductor		SMC-W	DNI
J1	2 Pos	Terminal Block, 2 Pos, 200 mil pitch		OSTTA024163	PWR_CONN2	1
J2		Single Line, 4 Pos, 100 mil pitch Header Connector	Sullins	PBC04SAAN	HDR1X4 0.100"	1
J3	4 Pos	Terminal Block, 4 Pos, 200 mil pitch			PWR_CONN4	1
J4	USB B	USB B Style Connector		67068-8000	USB B	1
J5	14 Pos Header	Header, 7-Pin, Dual row, Right Angle	Sullins	PBC07DAAN	HDR2X7 0.100"	1
J6	9 Pos Header	CONN HEADER .100 SINGL STR 9POS	Sullins	PBC09SAAN	HDR1X9 0.100"	1
JMP1	3 Pos Header	Single Line, 3 Pos, 100 mil pitch Header Connector	Sullins	PBC03SAAN	HDR1X3 0.100"	1
JP1, JP6	3 Pos Header	Single Line, 3 Pos, 100 mil pitch Header Connector	Sullins	PBC03SAAN	HDR1X3 0.100"	2
JP2, JP3, JP4, JP5	2 Pos Header	Single Line, 2 Pos, 100 mil pitch Header Connector	Sullins	PBC02SAAN	HDR1X2 0.100"	DNI
JP7	2 Pos Header	Single Line, 2 Pos, 100 mil pitch Header Connector	Sullins	PBC02SAAN	HDR1X2 0.100"	1
L1	10mH	Ferrite Bead 1.5A 40 ohm 0805 SMD	Steward	MI0805K400R-10	0805	1
PCB1	N/A	DRV8818EVM PCB Bare Board	N/A		4.5" X 5.5"	1
R1, R2	0.1	Resistor	Bourns	CRA2512-FZ-R100ELF	2512	2
R3	2.2K	Resistor	Yageo	RC0805JR-072K2L	0805	1
R4, R6	5K	Potentiometer	Murata Electronics	PV37Y502C01B00	6.4 mm X 6.7mm	2
R5, R7	47K	Resistor	Yageo	RC0805JR-0747KL	0805	2
R8	4.7K	Resistor	Yageo	RC0805JR-074K7L	0805	1
R9, R10	330	Resistor	Yageo	RC0805JR-07330RL	0805	2
R11	196K	Resistor	Yageo	9C08052A1963FKHFT	0805	1
R12	110K	Resistor	Yageo	RC0805JR-07110KL	0805	1
R101, R102, R103, R104, R105, R106, R107, R108, R109	3300	Resistor	Yageo	RC0603FR-073K3L	0603	9
S1	Push Button	Switch		EVQ-11A04M	Pana PB	1
SHNT1, SHNT2, SHNT3, SHNT4, SHNT5, SHNT6, SHNT7, SHNT8	Shunt	Shunt Jumper	Samtec	SNT-100-BK-T-H	0.100" (2.54mm)	8
TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13,	Test Stake White	Glass Beaded Test Point	Kobiconn	151-101-RC	TEST POINT 0.052"	23
TP14, TP15, TP16, TP17, TP18, TP19, TP20, TP21, TP22, TP30	Test Stake Wille	Glass Beaded Test Follit	Robicollii	151-101-NC	TEST FOINT 0.052	23
TP23, TP26, TP27, TP28, TP29		Glass Beaded Test Point	Kobiconn	151-103-RC	TEST POINT 0.052"	5
TP24, TP25	Test Stake Red	Glass Beaded Test Point	Kobiconn	151-107-RC	TEST POINT 0.052"	2
U1	Driver	Bipolar Stepper Motor Driver With Indexer	Texas Instruments	DRV8818PWPR	HTSSOP28	1
U2	USB Driver	USB Chip	FTDI	604-00043	28SSOP	1
U3	MSP430 MCU	MSP430 Microcontroller	Texas Instruments	MSP430F2617TPM	PQFP 64	1
U4	LDO	750 mA LDO 8-SOIC	Texas Instruments	TPS77701D	SOIC 8	1
Y1	Crystal	Crystal Oscillator	ECS Inc.	ECS-80-20-4	11.35 mm X 4.65 mm	1
N/A	Motor	High Torque (Square) Stepper Motor	Anaheim Automation, Inc.	23Y106S-LW8	NEMA 23	1

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